

MB2515_RF_Miniboard_STM32WBA25_QFN48_SMPS_USE

MB2515

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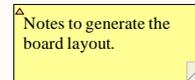
- Sheet 1: Project overview (this page)
- Sheet 2: Top
- Sheet 3: STM32 microcontroller I/Os & Clock
- Sheet 4: RF & Power Management

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



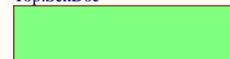
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U_Top
Top.SchDoc



HW1



MB2515

HW3



N/A

HW4

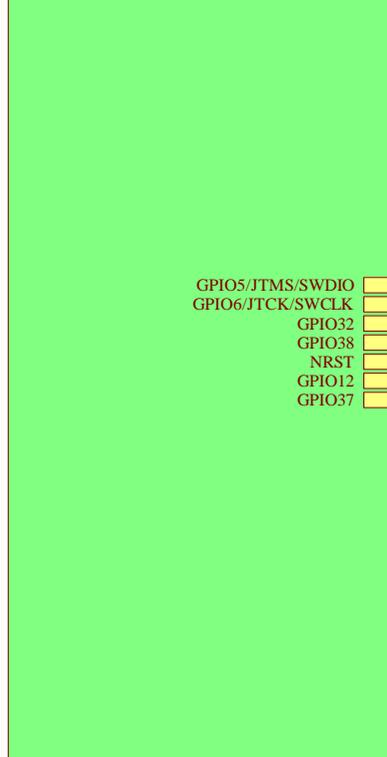


N/A

Title: Project Overview		
Project: MB2515_RF_Miniboard_STM32WBA25_QFN48_S		
Variant: WBA25CE		
Revision: A-01		Reference: MB2515
Size: A4	Date: 20-10-2025	Sheet: 1 of 4

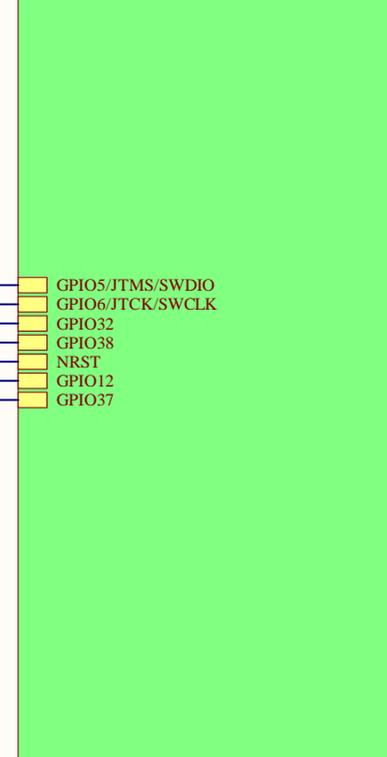


STM32 microcontroller I/Os & Clock

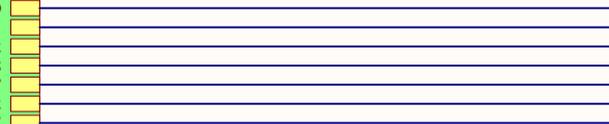


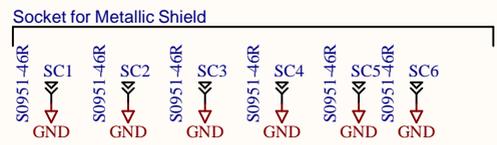
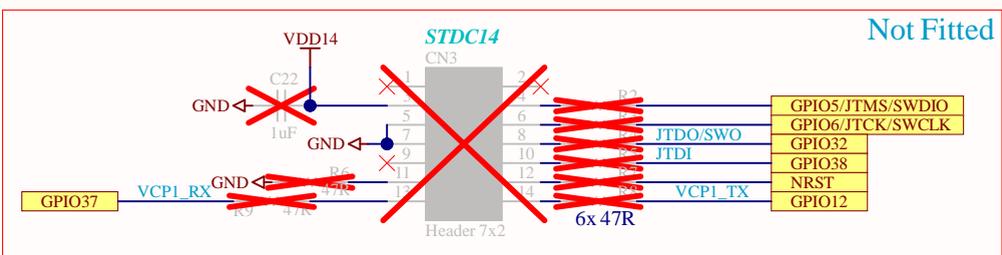
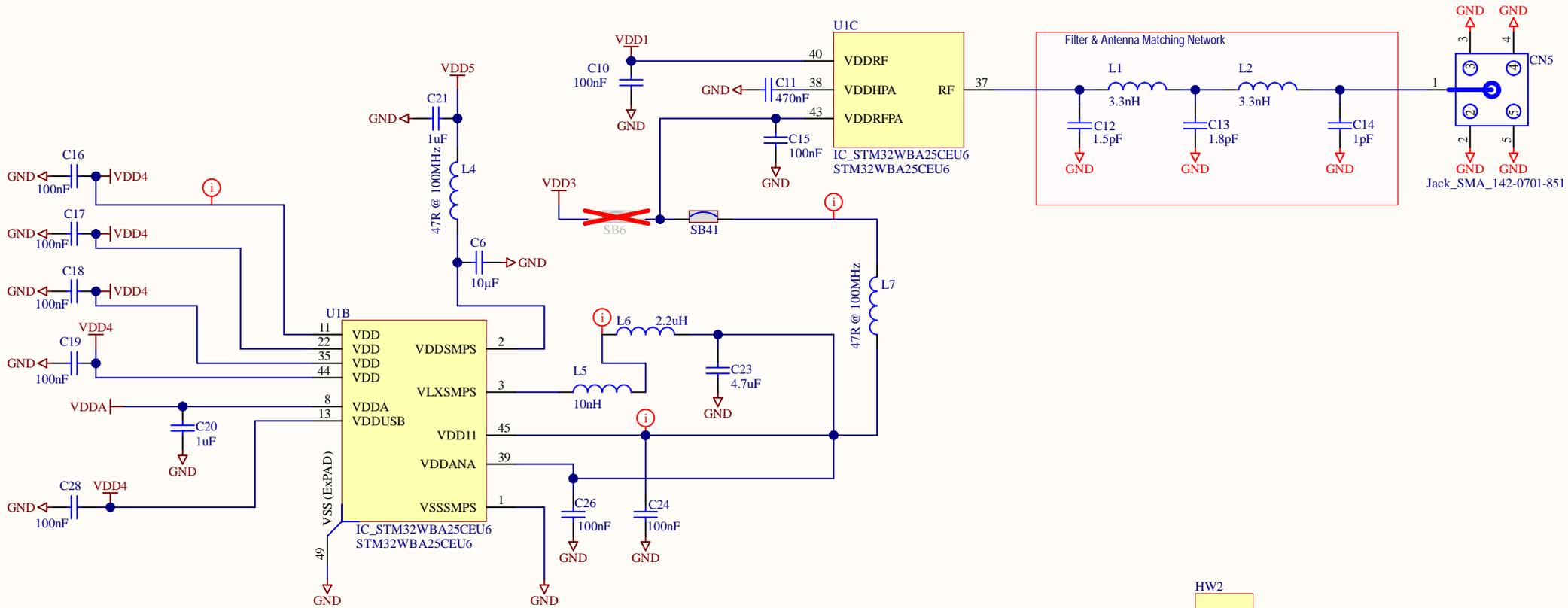
GPIO5/JTMS/SWDIO
GPIO6/JTCK/SWCLK
GPIO32
GPIO38
NRST
GPIO12
GPIO37

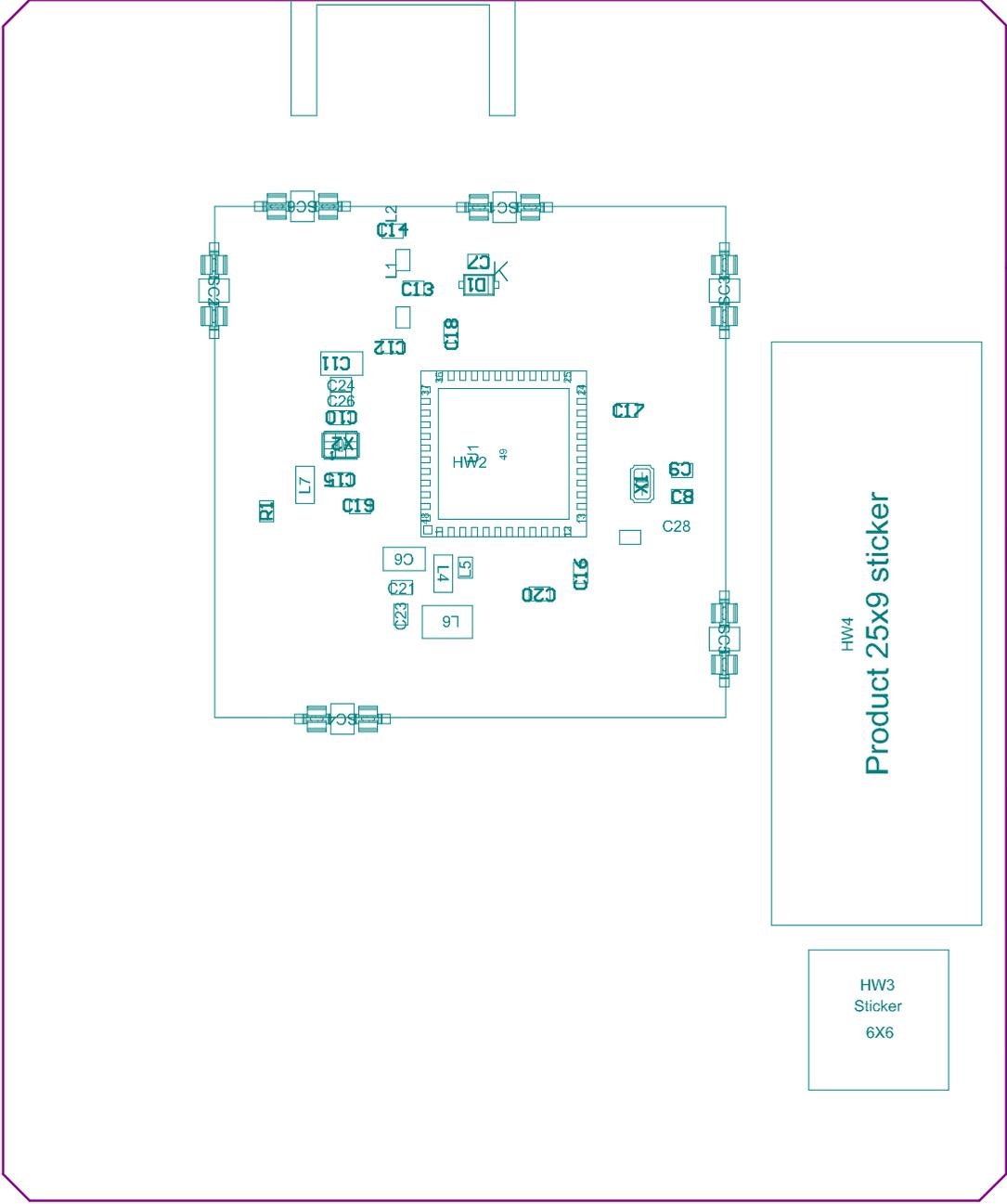
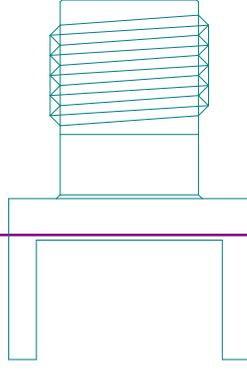
RF & Power Management Schematic



GPIO5/JTMS/SWDIO
GPIO6/JTCK/SWCLK
GPIO32
GPIO38
NRST
GPIO12
GPIO37

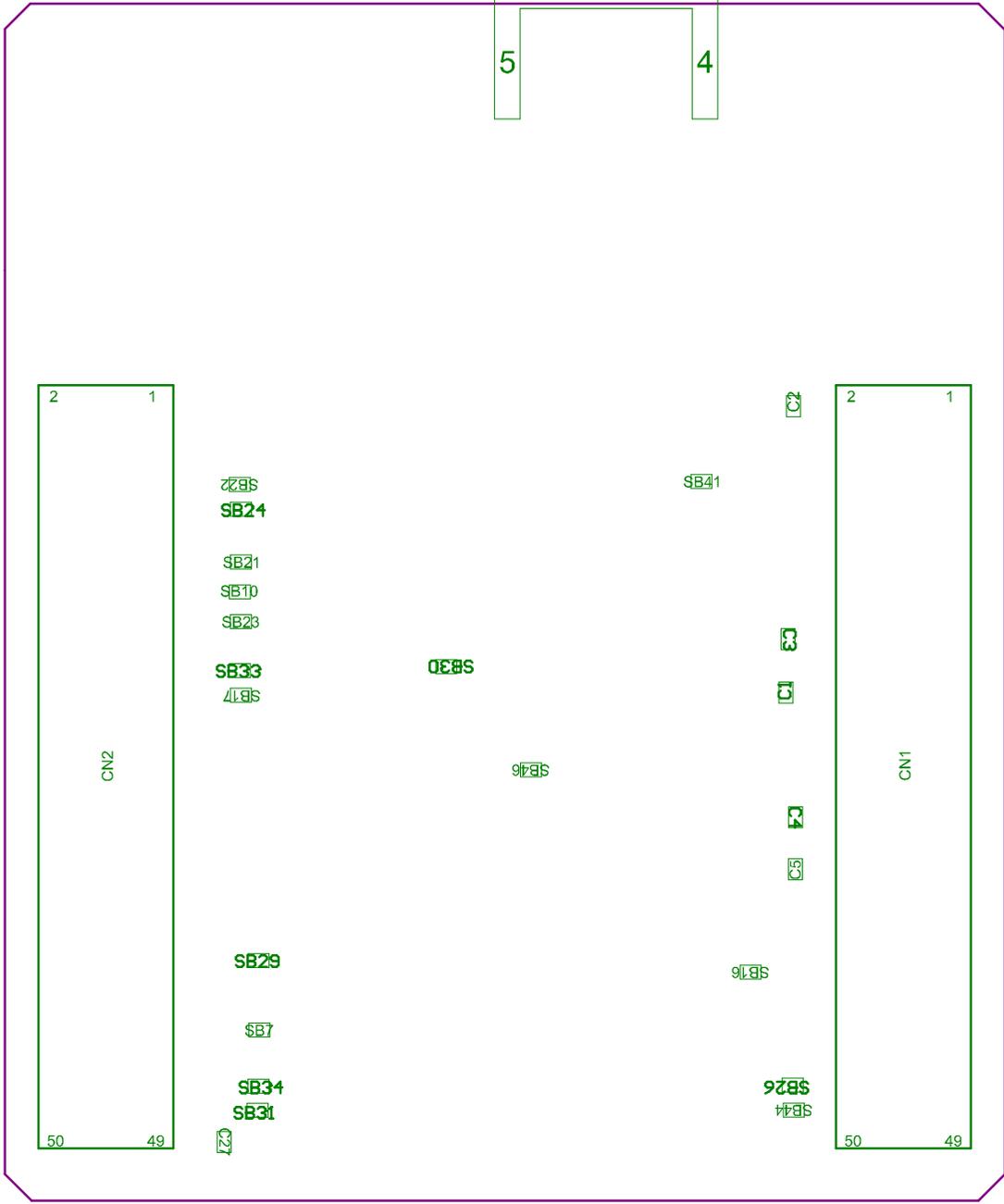
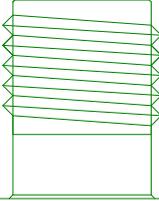


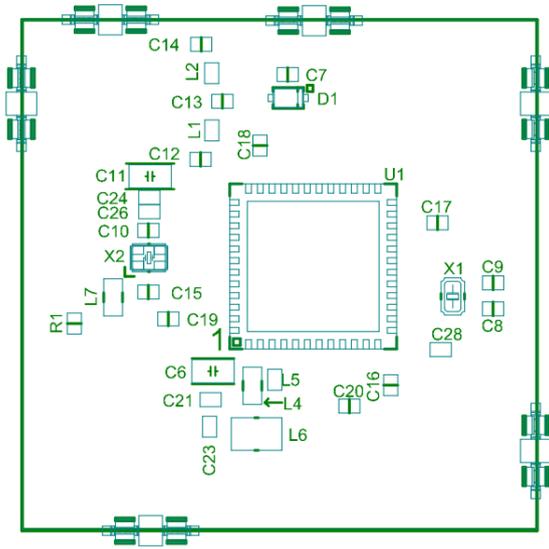
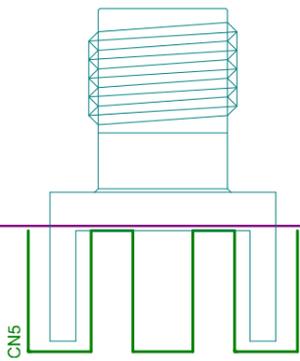




HW4
Product 25x9 sticker

HW3
Sticker
6X6





Product 25x9 sticker

Sticker
6X6

MB2515A

Product 25x9 sticker

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.018mm	4.2	
1	Top Layer		0.041mm		
	Dielectric 1	FR-4	0.076mm	3.7	
2	Internal 1		0.030mm		
	Dielectric 3	FR-4	1.270mm	4.2	
3	Internal 2		0.030mm		
	Dielectric 2	FR-4	0.076mm	3.7	
4	Bottom Layer		0.041mm		
	Bottom Solder	Solder Resist	0.018mm	4.2	
	Bottom Overlay				

1.600mm

Total board thickness:

